



## Material Content Data Sheet



<b>Sales Product Name</b>		BTS50050-1EGA		<b>Issued</b>		22. January 2018		
<b>MA#</b>		MA001686940						
<b>Package</b>		PG-DSO-12-16		<b>Weight*</b>		397.73 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	7.100	1.78	1.78	17850	17850
leadframe	inorganic material	phosphorus	7723-14-0	0.069	0.02		174	
	non noble metal	iron	7439-89-6	0.230	0.06		579	
wire	non noble metal	copper	7440-50-8	230.106	57.85	57.93	578551	579304
	noble metal	gold	7440-57-5	0.194	0.05		488	
encapsulation	non noble metal	aluminium	7429-90-5	1.409	0.35	0.40	3542	4030
	organic material	carbon black	1333-86-4	0.296	0.07		745	
	plastics	epoxy resin	-	21.184	5.33		53262	
leadfinish	inorganic material	silicondioxide	60676-86-0	126.659	31.85	37.25	318455	372462
	non noble metal	tin	7440-31-5	4.235	1.06	1.06	10649	10649
plating	noble metal	silver	7440-22-4	1.852	0.47	0.47	4656	4656
glue	plastics	Polyimide	26023-21-2	0.205	0.05	0.05	514	514
solder	non noble metal	tin	7440-31-5	0.084	0.02		211	
	noble metal	silver	7440-22-4	0.105	0.03		263	
	non noble metal	lead	7439-92-1	4.001	1.01	1.06	10061	10535
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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